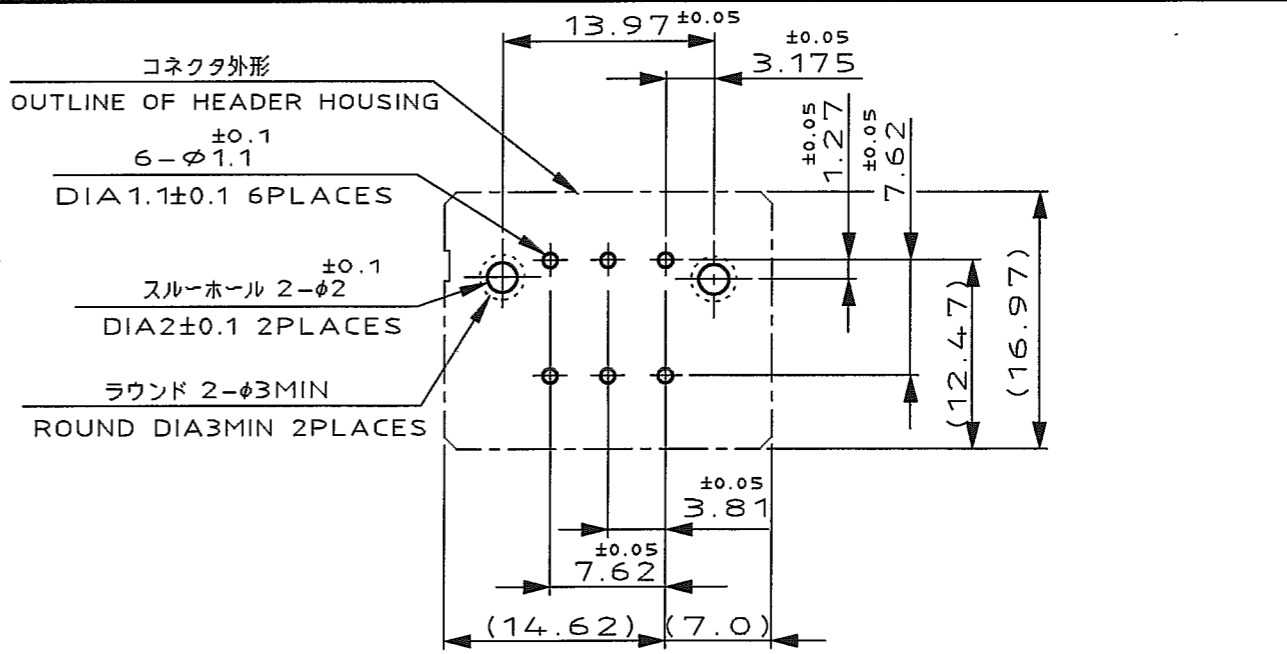
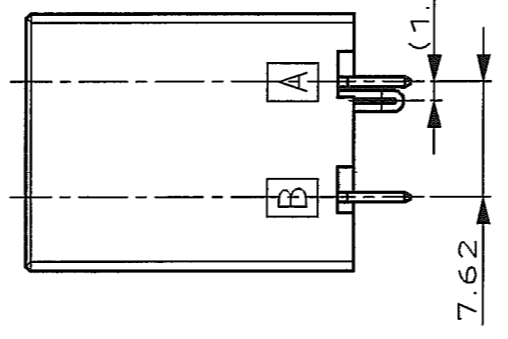
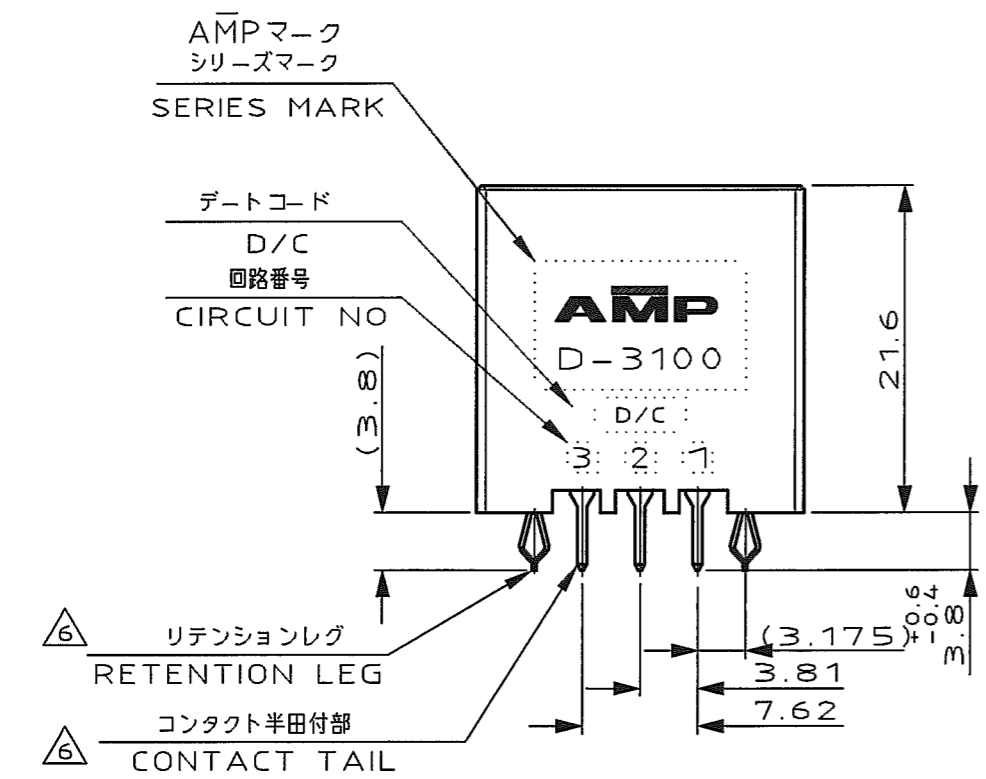
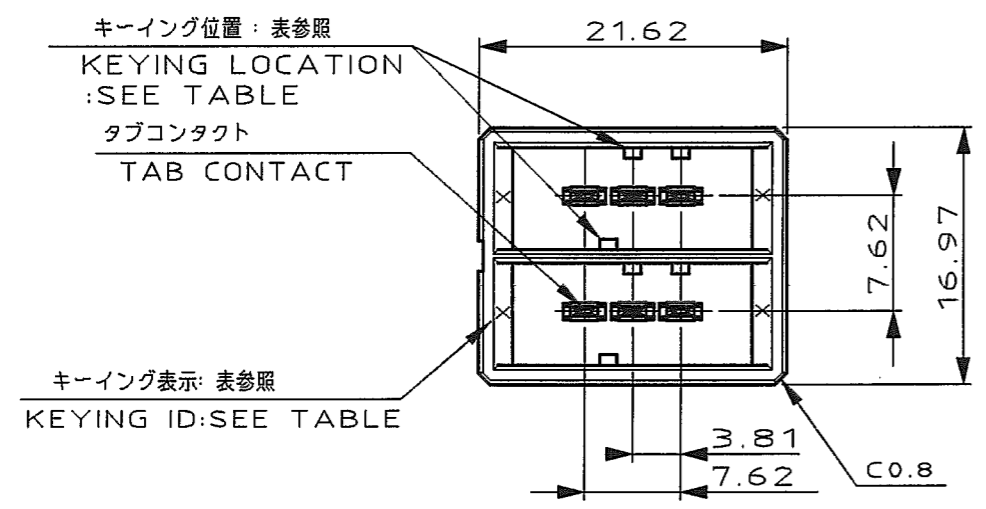


NUMBER 178141  
 METRIC  
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT  
 PRINT DIST



推奨基板取付け穴寸法  
 PC 基板厚: 1.6±0.1  
 (非累積公差)  
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN  
 PC BOARD THICKNESS: 1.6±0.1  
 (NOT ACCUMULATE TOLERANCE)  
 (CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK  
 CONTACT: COPPER ALLOY  
 RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒  
 コネクタ: 銅合金  
 リテンションレグ: 銅合金
- めっき: コネクタ: 全面Ni下地  
 接触部: 0.38 μm MIN金めっき
- めっき: コネクタ: 全面Ni下地  
 接触部: 0.76 μm MIN金めっき
- めっき: コネクタ: 全面Ni下地  
 接触部: 2.0 μm MINスズめっき
- めっき: リテンションレグとコネクタ半田付部  
 ニッケル下地の上に半田めっき
- めっき: リテンションレグとコネクタ半田付部  
 ニッケル下地の上にスズめっき

A ROW		X	Y	△6	△4	3-178141-5
B ROW				△6	△3	3-178141-3
A ROW		X	X	△6	△4	1-178141-5
B ROW				△6	△3	1-178141-3
				△6	△2	1-178141-2
KEYING LOCATION		A ROW KEYING	B ROW KEYING	FINISH		製品番号 PART NO.



WIRE RANGE	INSULATION DIA	NAME	
mm²(AWG - )	mmφ	DYNAMIC D-3100 3.81X7.62PITCH(V) 6 POS.HDR CONN.ASS'Y	
MATERIAL SEE NOTE 注記参照	FINISH SEE NOTE 注記参照	一般公差 (GENERAL TOLERANCE)	SIZE LOC NUMBER
DR. 19 APR 94 N. Matsubara	DE. 19 APR 94 N. Matsubara	100% ±0.3 100% 300% ±0.4 300% 100% ±0.45 角度: ±3'	A3 J C-178141
LTR REVISION RECORD	DR CHK DATE	CHK. 20 APR 94 S. MANABE	APP. 20 APR 94 S. MANABE
E1 REVISED PER ECO-11-005030	RK HMR 28MAR 11	SCALE 2-1	REV. E1 SHEET 1 OF 1

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)